



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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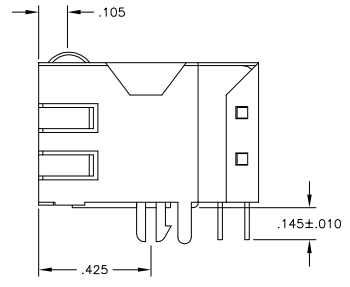
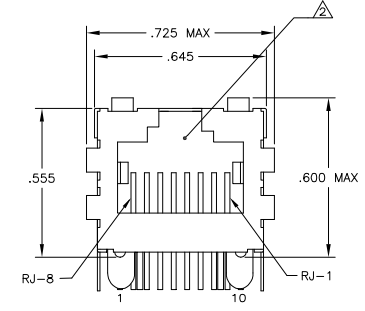
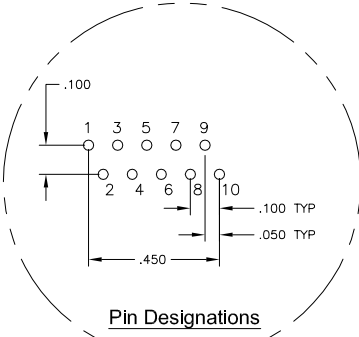
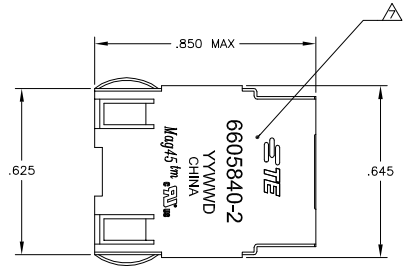
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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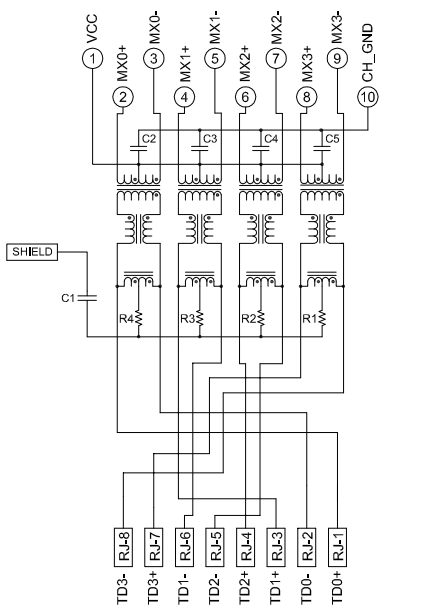


LOC	DATE	REVISIONS	DATE	BY	APP
AA	22				
B	ECO-08-031922		10DEC2008	VL	LR
C	ECO-11-013915		30MAY2011	EL	LR

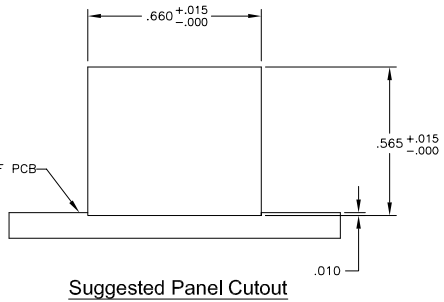
MECHANICAL:



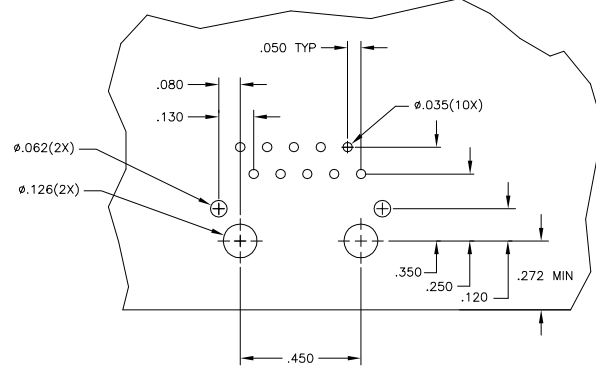
ELECTRICAL:
7G05P1 GIGABIT MAGNETIC CIRCUIT



C1 = 1000pF, 2kV DECOUPLING CAPACITOR
R1-R4 = 75 OHMS, 1/16 W RESISTORS
C2-C5 = 0.1 uF, 10%, 50V CAPACITORS



Suggested PCB Layout
(Component Side)



- ⚠ MATERIALS:
HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0.
SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30µINCH MIN SEMI-BRIGHT NICKEL; SOLDER TABS POST DIPPED WITH 100µINCH MIN SAC SOLDER.
MOD JACK CONTACTS - .0157" x .018" THICK, PHOSPHOR BRONZE, 50µINCH MIN OVERALL NICKEL UNDERPLATE, WITH SELECT 50µINCH MIN HARD GOLD FINISH PLATE. SOLDER TAILS WITH 100µINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
- ⚠ RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.
- ⚠ MAGNETICS
-APPLICATION: 10/100/1000 BASE-T
-IMPEDANCE: 100 OHMS
-TURNS RATIO (CHIP-CABLE): 1:1 ALL FOUR PAIRS
-OPEN CIRCUIT INDUCTANCE (OCL): 350uH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, ALL FOUR PAIRS
-ALL FOUR PAIRS BI-DIRECTIONAL
-PERFORMANCE @ 25°C:
INSERTION LOSS (IL): 11dB MAX FROM 0.5MHz TO 100MHz
RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 40MHz
12-20LOG(f/80)dB MIN FROM 4.01MHz TO 100MHz
CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
33-20LOG(f/50)dB MIN FROM 4.01MHz TO 100MHz
COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
-ISOLATION VOLTAGE: 225VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC.
- 4. OPERATING TEMPERATURE: FROM 0° C TO +70° C.
- ⚠ ALL DIMENSIONS NOMINAL UNLESS OTHERWISE NOTED.
- ⚠ INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL, AND THEREFORE ARE AUTO-MD/MDIX CAPABLE.
- ⚠ TE CONNECTIVITY LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
- 8. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX, 10 SECONDS MAX.

6605840-2
PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		REV: GRZYBOWSKI	OLJAN2008	TE Connectivity	
DIMENSIONS: INCHES		REV: GRZYBOWSKI	OLJAN2008	1X1 MA645(TN), 704P1 (10 PIN HORIZONTAL) SCHEMATIC, 7G05P1 GIGABIT MAGNETIC CIRCUIT, SHIELDED, WITH DECOUPLING CAPACITOR, NO LEADS	
MATERIAL: -		FINISH: -	WEIGHT: -	SIZE: A1	DATE CODE: 00779
DRAWING NO: 108-2100		DRAWING NO: 108-2100		DRAWING NO: 108-2100	
SCALE: NTS		SCALE: NTS		SCALE: NTS	